

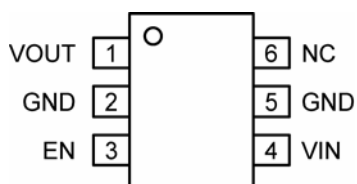
Ordering Information

Part Number		Part Marking ⁽¹⁾		Soft-Start	Load Discharge	Package
Standard	Pb-Free	Standard	Pb-Free			
—	MIC94064YC6 ⁽¹⁾	—	64P	•		SC-70-6
—	MIC94065YC6 ⁽¹⁾	—	6P5	•	•	
—	MIC94064YMT	—	P64	•		1.2mm x 1.6mm Thin MLF [®]
—	MIC94065YMT	—	P65	•	•	

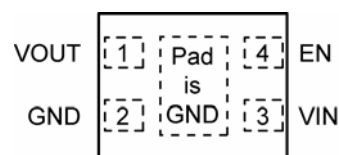
Notes

- Underbar symbol on SC-70 Pb-free packages may not be to scale.

Pin Configuration



SC-70-6 (C6)



Top View

1.2x1.6 mm Thin MLF[®] (MT)

Pin Description

Pin Number		Pin Name	Pin Function
SC-70	MLF		
1	1	V _{OUT}	Drain of P-channel MOSFET.
2,5	2	GND	Ground and the backside pad (MLF only) should both be connected to electrical ground.
4	3	V _{IN}	Source of P-channel MOSFET.
3	4	EN	Enable (Input): Active-high CMOS compatible control input for switch A. Do not leave floating.
6	--	NIC	No Internal Connection. A signal or voltage applied to this pin will have no effect on device operation.

Absolute Maximum Ratings ⁽¹⁾

Input Voltage (V_{IN})	+6V
Enable Voltage (V_{EN})	+6V
Continuous Drain Current (I_D) ⁽³⁾	
$T_A = 25^\circ\text{C}$	$\pm 2\text{A}$
$T_A = 85^\circ\text{C}$	$\pm 1.4\text{A}$
Pulsed Drain Current (I_{DP}) ⁽⁴⁾	$\pm 6\text{A}$
Continuous Diode Current (I_S) ⁽⁴⁾	–50mA
Storage Temperature (T_S)	–55°C to +150°C
EDS Rating – HBM ⁽⁶⁾	4KV

Operating Ratings ⁽²⁾

Input Voltage (V_{IN})	+1.7 to +5.5V
Junction Temperature (T_A)	–40°C to +125°C
Package Thermal Resistance	
SC-70-6 (θ_{JA})	240°C/W
1.2x1.6 MLF [®] (θ_{JA})	172°C/W
1.2x1.6 MLF [®] (θ_{JC}) ⁽³⁾	134°C/W

Electrical Characteristics

$V_{IN} = 5\text{V}$; $T_A = 25^\circ\text{C}$, bold values indicate $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{EN_TH}	Enable Threshold Voltage	$V_{IN} = 1.8\text{V to } 4.5\text{V}$, $I_D = -250\mu\text{A}$	0.5		1.2	V
		$V_{IN} = 1.7\text{V to } 4.5\text{V}$, $I_D = -250\mu\text{A}$	0.4		1.2	V
I_{EN}	Enable Input Current	$V_{IN} = V_{EN} = 5.5\text{V}$		2	4	μA
I_{VIN}	OFF State Leakage Current	$V_{IN} = +5.5\text{V}$, $V_{EN} = 0\text{V}$			1	μA
$R_{DS(ON)}$	P-Channel Drain to Source ON Resistance SC-70 Package	$V_{IN} = +4.5\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		77	110	m Ω
		$V_{IN} = +3.6\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		85	115	m Ω
		$V_{IN} = +2.5\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		100	140	m Ω
		$V_{IN} = +1.8\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		145	200	m Ω
		$V_{IN} = +1.7\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		155	215	m Ω
$R_{DS(ON)}$	P-Channel Drain to Source ON Resistance MLF Package	$V_{IN} = +4.5\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		85	115	m Ω
		$V_{IN} = +3.6\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		100	140	m Ω
		$V_{IN} = +2.5\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		145	200	m Ω
		$V_{IN} = +1.8\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		155	215	m Ω
		$V_{IN} = +1.7\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		165	225	m Ω
$R_{SHUTDOWN}$	Turn-Off Resistance	$V_{IN} = +3.6\text{V}$, $I_{TEST} = 1\text{mA}$, $V_{EN} = 0\text{V}$ MIC94065		200	300	Ω

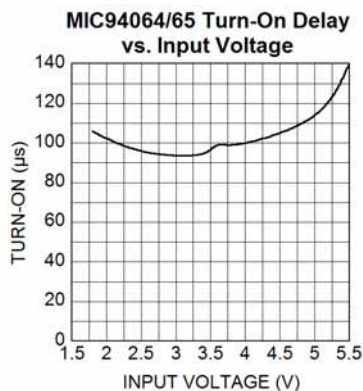
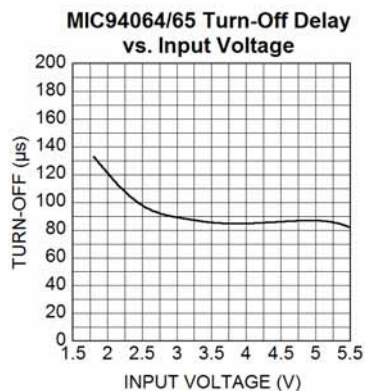
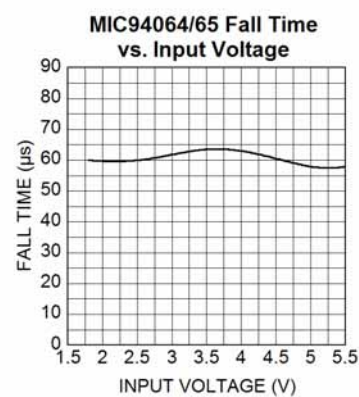
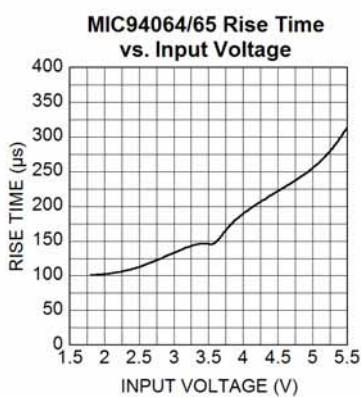
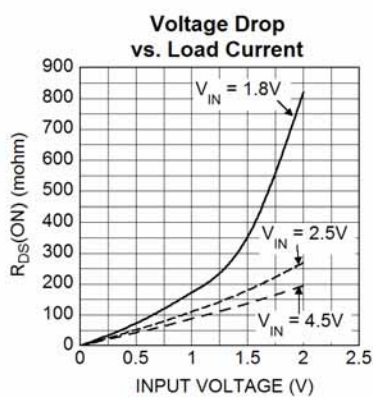
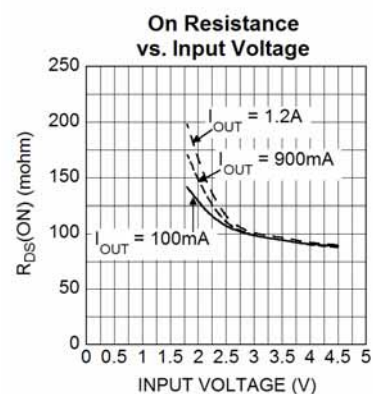
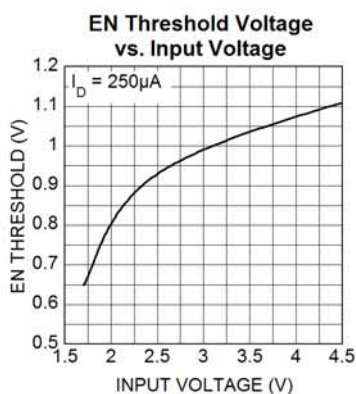
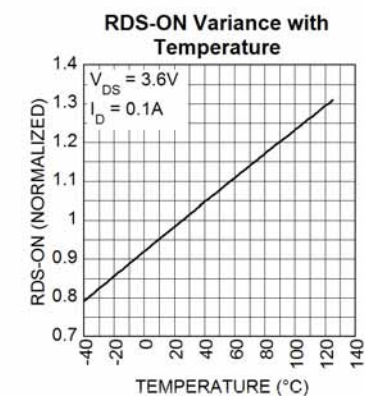
Dynamic

Symbol	Parameter	Condition	Min	Typ	Max	Units
t_{ON_DLY}	Turn-On Delay Time	$V_{IN} = +3.6\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$	80	125	170	μs
t_{ON_RISE}	Turn-On Rise Time	$V_{IN} = +3.6\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$	75	115	150	μs
t_{OFF_DLY}	Turn-Off Delay Time	$V_{IN} = +3.6\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		100	200	ns
t_{OFF_FALL}	Turn-Off Fall Time	$V_{IN} = +3.6\text{V}$, $I_D = -100\text{mA}$, $V_{EN} = 1.5\text{V}$		25	100	ns

Notes:

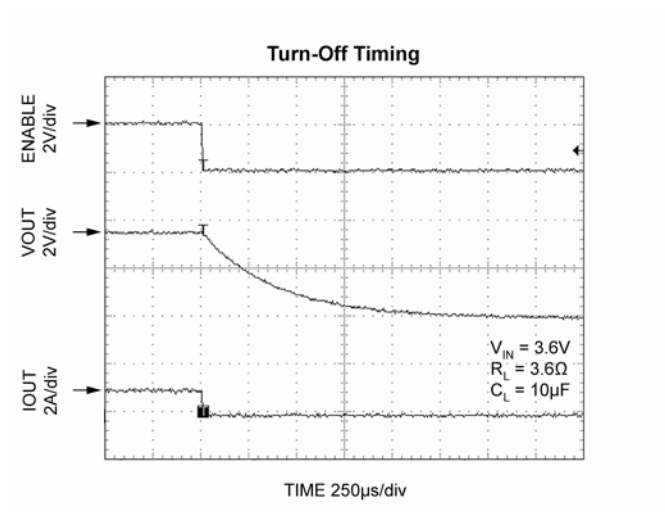
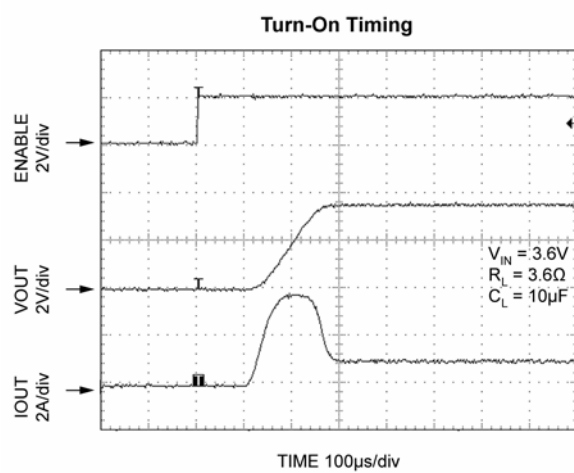
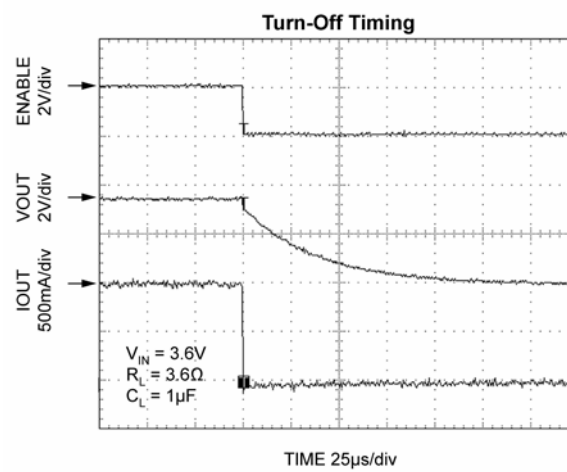
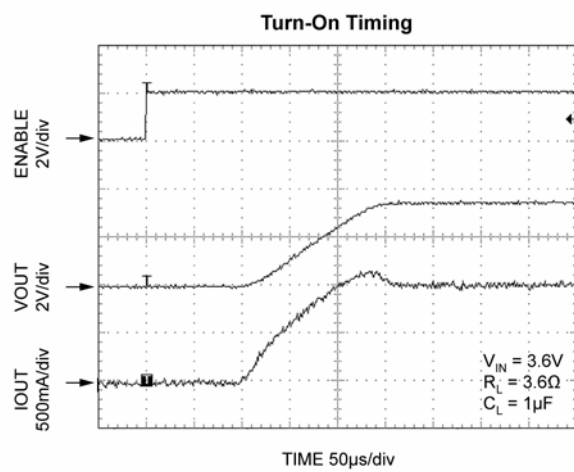
- Exceeding the absolute maximum rating may damage the device.
- The device is not guaranteed to function outside its operating rating.
- With backside thermal contact to PCB.
- Pulse width <300 μs with < 2% duty cycle.
- Continuous body diode current conduction (reverse conduction, i.e. V_{OUT} to V_{IN}) is not recommended.
- Devices are ESD sensitive. Handling precautions recommended. HBM (Human body model), 1.5k in series with 100pF.

Typical Characteristics

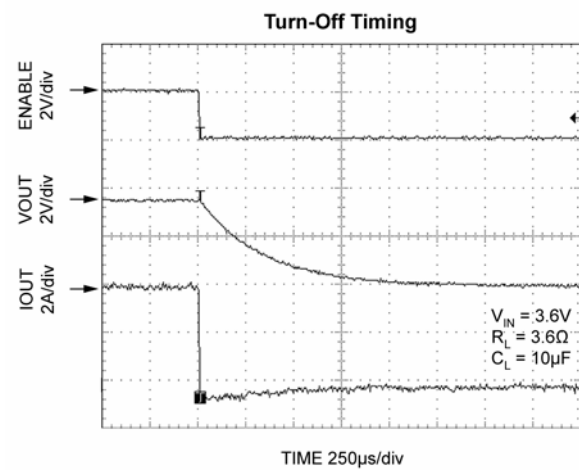
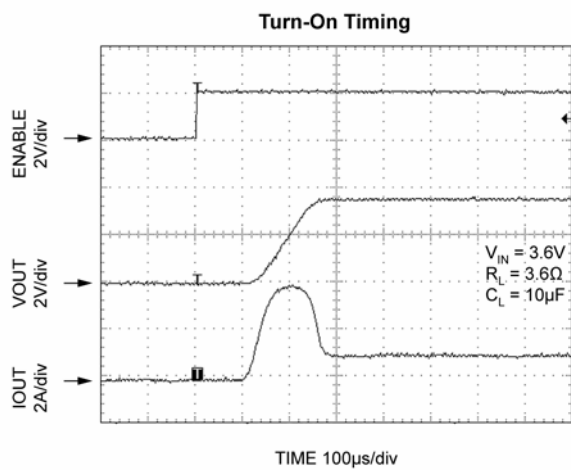
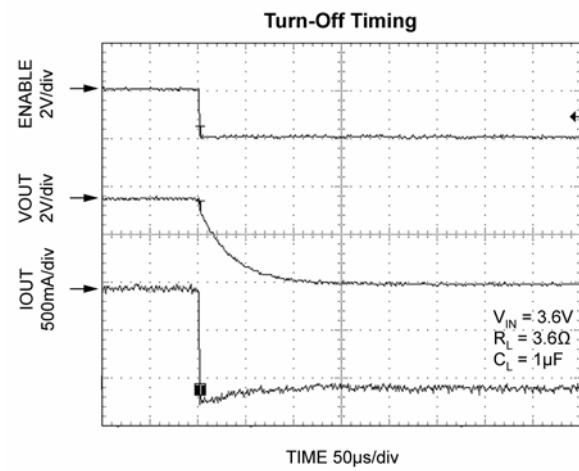
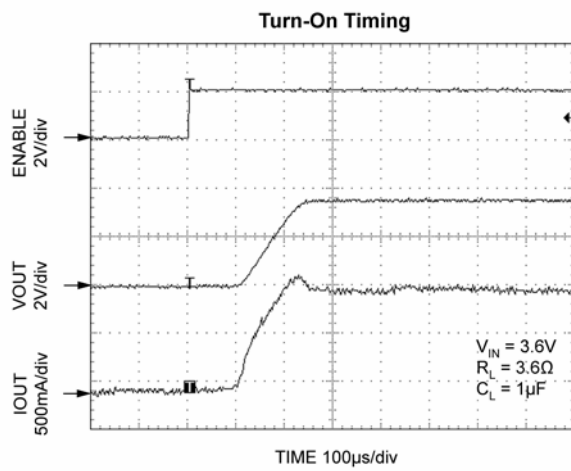


Functional Characteristics

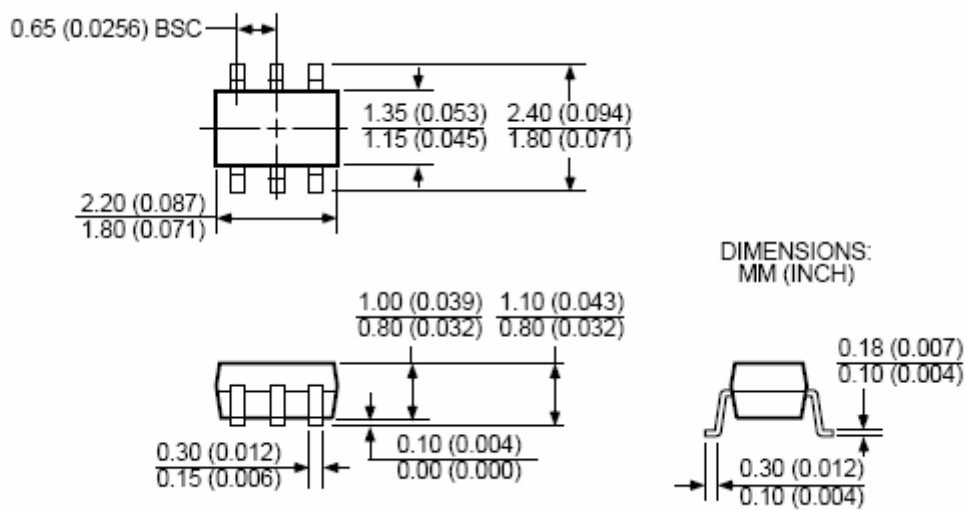
MIC94064



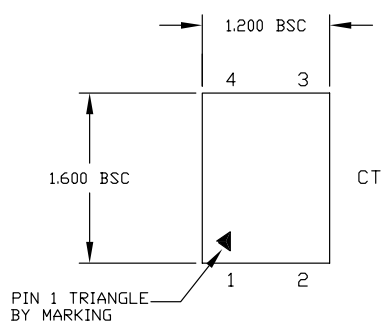
MIC94065



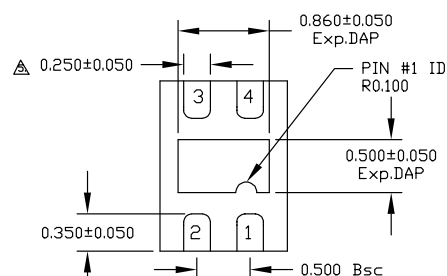
Package Information



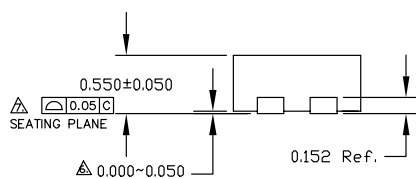
6-Pin SC-70 (C6)



TOP VIEW



BOTTOM VIEW

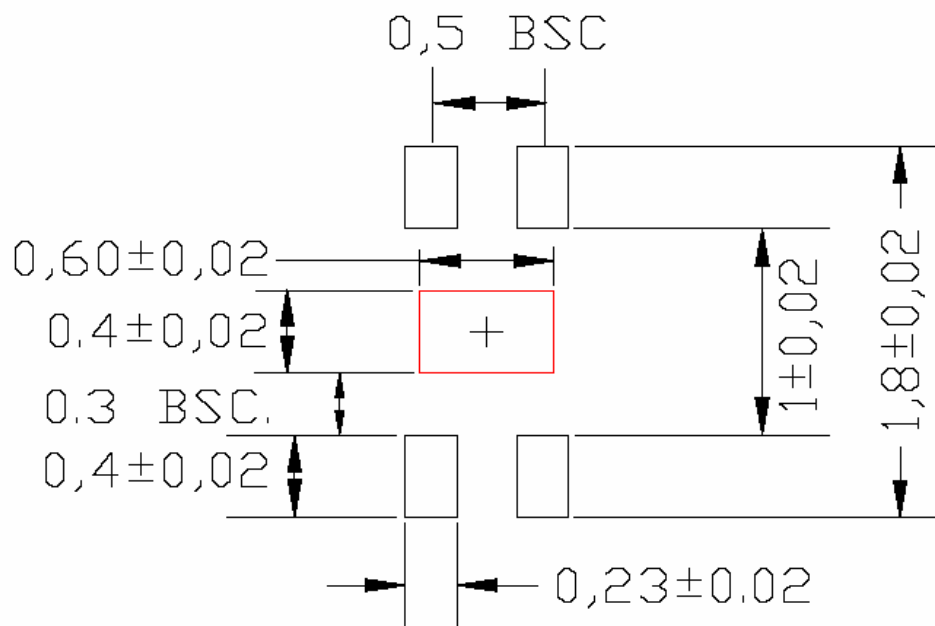


SIDE VIEW

- NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. MAX. PACKAGE WARPAGE IS 0.05 mm.
 3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
 4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.
- △ DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.
- △ APPLIED ONLY FOR TERMINALS.
- △ APPLIED FOR EXPOSED PAD AND TERMINALS.

4-Pin Thin MLF® (MT)

Recommended Land Pattern for MLF[®] 1.2x1.6 4 Lead



Optional for maximum thermal performance, heatsink should be connected to GND plane of PCB for maximum thermal performance.

Disclaimer: This is only a recommendation based on information available to Micrel from its suppliers. Actual land pattern may have to be significantly different due to various materials and processes used in PCB assembly. Micrel makes no representation or warranty of performance based on the recommended land pattern."

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